

GENERAL ELECTRICAL REQUIREMENTS

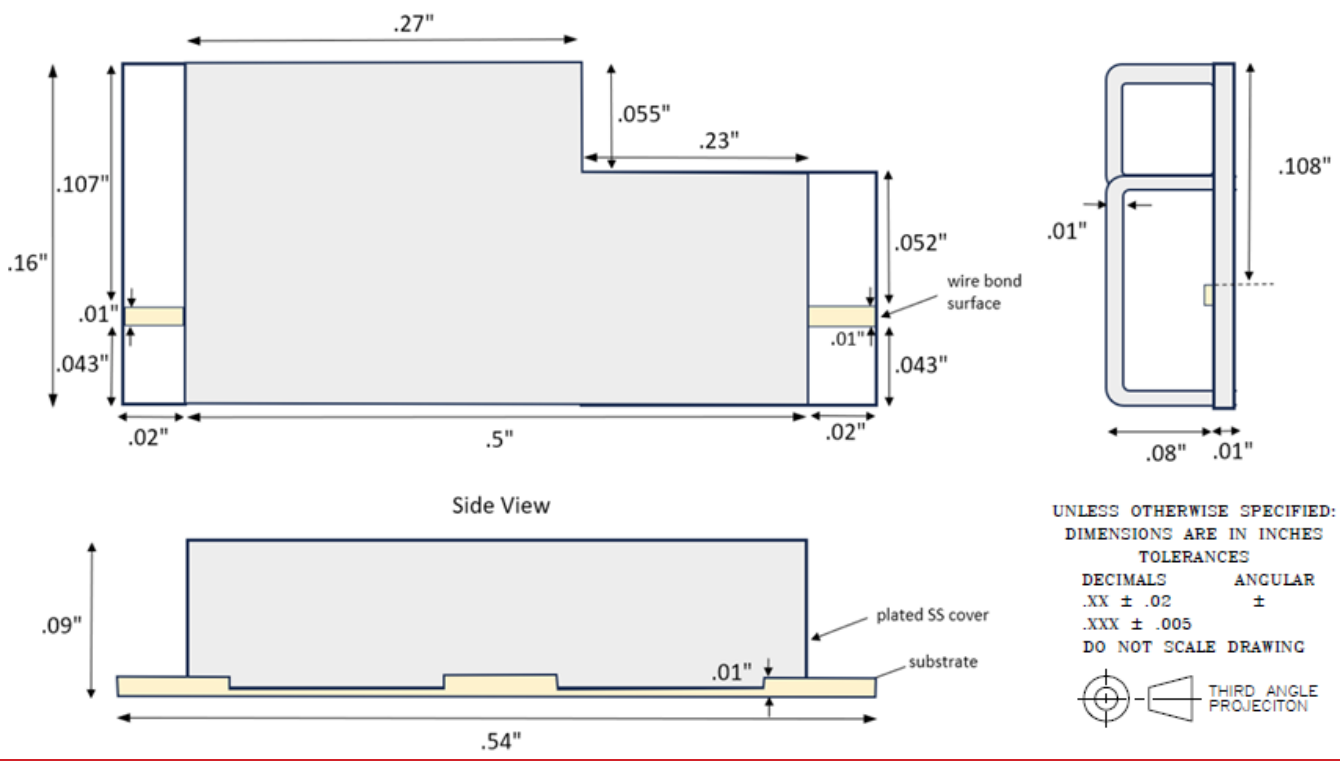
| Parameter | Symbol | Min. | Typ. | Max. | Units | Conditions |
|------------------------|--------|---|------|-------|-------|------------|
| Center Frequency | | 10.80 | | | GHz | |
| Passband Width | | 10.55 | | 11.05 | GHz | |
| In band Insertion Loss | | | | 2.5 | dB | |
| Rejection | | | | | | |
| @ DC to 1.45GHz | | 25 | | | dB | |
| @ 1.45 to 9.60GHz | | 30 | | | dB | |
| @ 12.00 to 12.95GHz | | 35 | | | dB | |
| @ 12.95 to 13.45GHz | | 55 | | | dB | |
| @ 14.40 to 37.45GHz | | 40 | | | dB | |
| @ 37.45 to 40.00GHz | | 35 | | | dB | |
| Package | | | | | | |
| Dimensions | | 0.54 x 0.16 x 0.09 | | | Inch | |
| Package Type | | Wire-bondable pads for hybrid application | | | | |
| Substrate Thickness | | 10 | | | mil | |

ENVIRONMENTAL CONDITIONS

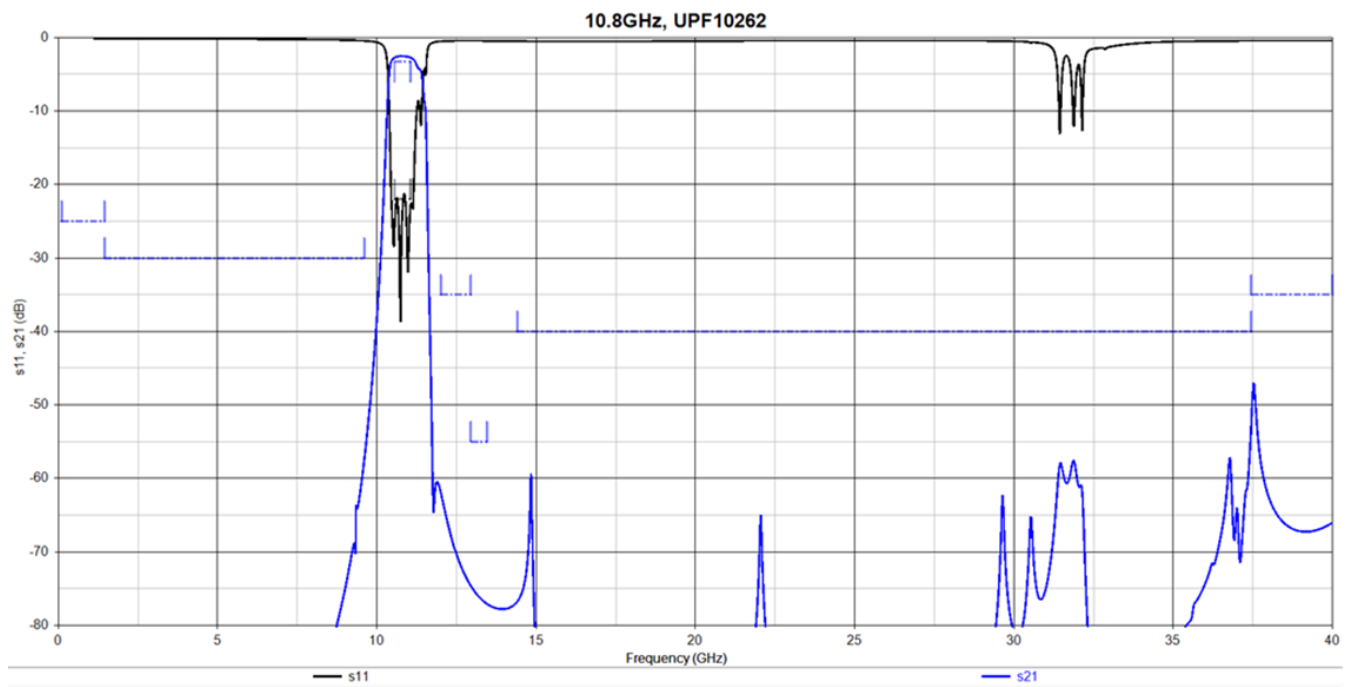
| Parameter | Symbol | Min. | Typ. | Max. | Units | Conditions |
|-----------------------|----------------|------|------|------|-------|------------|
| Operating Temperature | T _A | -40 | | +85 | °C | |
| Pin | | | | 0 | dBm | |

PACKAGE OUTLINE

10.8GHz



SIMULATED PLOT



| Data Sheet Revision Table | | | |
|---------------------------|-----|--------|---------------------|
| Date | Rev | Author | Details of Revision |
| 01/26/24 | A | AR | Original Release |